



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC040N08NS5		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001239708						
<b>Package</b>		PG-TDSON-8-7		<b>Weight*</b>		119.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.096	0.92	0.92	9207	9207
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		318	
wire	non noble metal	copper	7440-50-8	37.762	31.71	31.75	317186	317599
	noble metal	gold	7440-57-5	0.044	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		727	
	plastics	epoxy resin	-	6.143	5.16		51600	
leadfinish	inorganic material	silicondioxide	60676-86-0	37.032	31.11	36.34	311056	363383
	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12193	12193
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1390	1390
solder	non noble metal	tin	7440-31-5	0.031	0.03		263	
	noble metal	silver	7440-22-4	0.039	0.03		329	
heatspreader	non noble metal	lead	7439-92-1	1.496	1.26	1.32	12568	13160
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.51	9.52	95085	95209
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
*deviation	non noble metal	copper	7440-50-8	22.292	18.72	18.75	187243	187486
	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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